

Gregor
#2 and
8-10-98
J. Hanale
PATENT 7000
TESSERA 3.3-018 CONT CONT II CONT 8-10-98

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of
Khandros et al.

Group Art Unit:

Serial No.: Unassigned

Examiner:

Filed: On Even Date Herewith

Date: July 6, 1998

For: Face-Up Semiconductor
Chip Assembly

X

Assistant Commissioner For Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir or Madame:

Preliminary to the initiation of the prosecution of the above-identified pending U.S. patent application, the following amendments and remarks are respectfully submitted.

In the Title:

Please amend the title of the application to: --Face-up
Semiconductor Chip Assembly --.

In the Specification:

Please insert before the first line, after the title, the following:

CROSS-REFERENCE TO RELATED APPLICATIONS

This is a continuation of United States Patent Application No. 08/861,280, filed on May 21, 1997 which is in turn a continuation of United States Patent Application No. 08/319,966, filed on October 7, 1994, now United States Patent No. 5,685,885. United States Patent Application No. 08/319,966 is a

EXPRESS MAIL LABEL NUMBER: EM411073384US